

forming a metal plating layer (95) on said first and said second metal foils of both sides of said intermediate printed wiring board, on an inner wall of said through hole, on said corner rounded portion, and on an exposed surface of said second metal foil exposed through the bottom of said through hole to obtain a final printed wiring board provided with interlayer connection.

an insulator substrate (1a) having a first principal surface and a second principal surface opposite to said first principal surface; and

said insulator substrate having a through hole (86) which is formed therein and extends in a direction substantially perpendicular to said first and said second principal surfaces so that a part of a surface of said first metal layer is exposed as an exposed surface through a bottom (92) of said through hole;

said printed wiring board comprising a second metal layer (95) formed on said first principal surface of said insulator substrate, on an inner wall of said through hole, and on said exposed surface of the first metal layer.